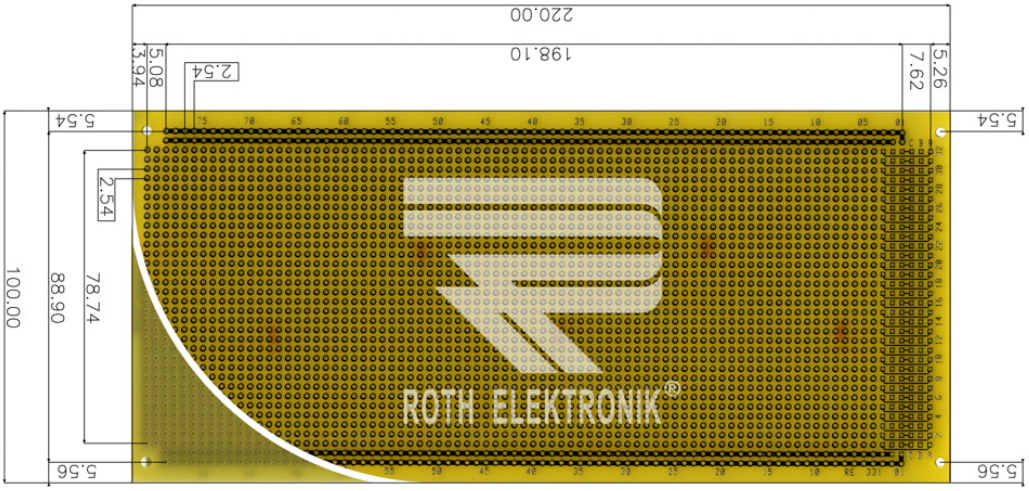

RE331-LF

- System Multibus II
- Epoxy fibre-glass FR4 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-leadfree)
- Hole spacing 2.54 x 2.54 mm
- 32 x 81 soldering pads 2.00 mm Ø
- Hole diameter 1.00 mm
- Connector 32/64/96-channel DIN 41612 type C
- Size 100 x 220 mm

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